



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 197 FR4 35 L36.70 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-2	70 μ	Copper			A1
	360 μ	L-FR4			
Layer-3	70 μ	Copper			B
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-4	100 μ	Prepreg			
	70 μ	Copper			
	360 μ	L-FR4			
Layer-5	70 μ	Copper		B	
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	100 μ	Prepreg			
	35 μ	Copper			
	35 μ	Copper			